



Material Content Data Sheet



Sales Product Name		BTS50060-1EGA		Issued		9. January 2019		
MA#		MA004508940						
Package		PG-DSO-12-16		Weight*		397.69 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	5.480	1.38	1.38	13779	13779
chip_2	inorganic material	silicon	7440-21-3	1.620	0.41	0.41	4074	4074
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		174	
	non noble metal	iron	7439-89-6	0.230	0.06		579	
wire	non noble metal	copper	7440-50-8	230.106	57.85	57.93	578614	579367
	noble metal	gold	7440-57-5	0.194	0.05		488	
encapsulation	non noble metal	aluminium	7429-90-5	1.407	0.35	0.40	3537	4025
	organic material	carbon black	1333-86-4	0.296	0.07		745	
	plastics	epoxy resin	-	21.184	5.33		53268	
leadfinish	inorganic material	silicondioxide	60676-86-0	126.660	31.85	37.25	318493	372506
	non noble metal	tin	7440-31-5	4.235	1.06	1.06	10650	10650
plating	noble metal	silver	7440-22-4	1.852	0.47	0.47	4656	4656
solder	non noble metal	tin	7440-31-5	0.083	0.02		209	
	noble metal	silver	7440-22-4	0.104	0.03		261	
glue	non noble metal	lead	7439-92-1	3.962	1.00	1.05	9963	10433
	plastics	Polyimide	26023-21-2	0.203	0.05	0.05	510	510
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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